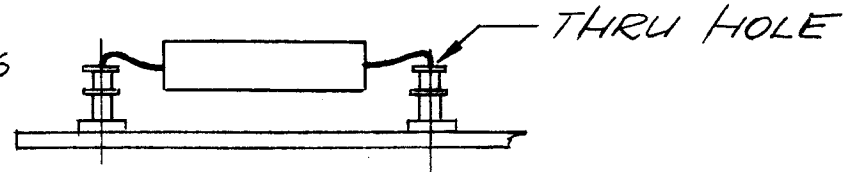
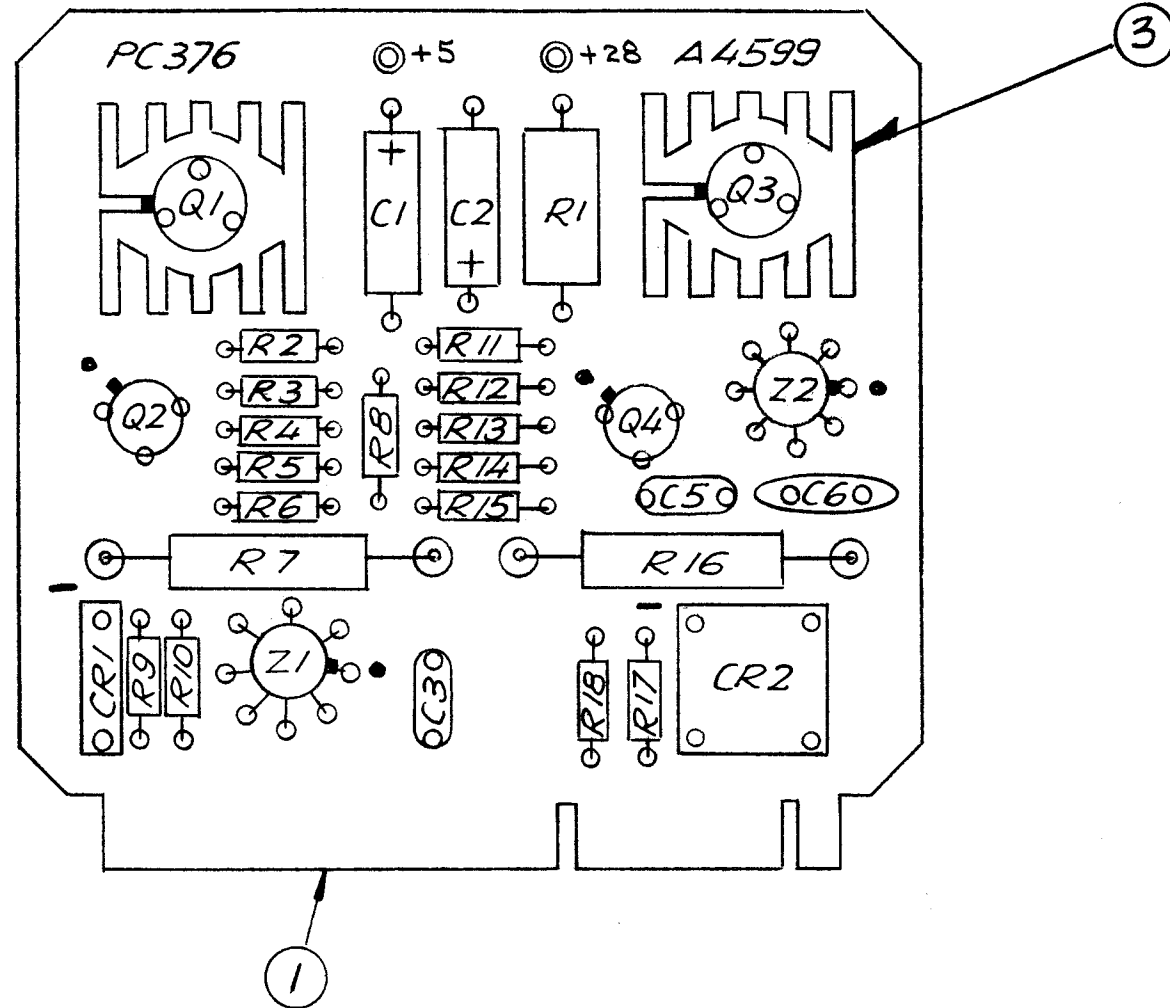


MOUNTING FOR R7 & R16



REVISIONS						
ZONE	LTR	DESCRIPTION	DATE	E.M.N.NO	DRAFT	CHKD APPD
	X	EXP RELEASE	9/2/69		KH.	
	Ø	ORIGINAL RELEASE FOR PRODUCTION	9/15/69		CU	



ASSEMBLY NOTES:

1. TO MOUNT COMPONENTS INSERT LEAD THROUGH PLATED THRU-HOLES.
2. CAUTION; WHEN APPLYING HEAT AND SOLDER TO LEAD AND FOIL.
3. CLEAN AND INSPECT AS PER SPEC S 676.
4. FOR ELECTRICAL COMPONENT PART NUMBERS REFER TO NPL A 4599.
5. USE SYMBOL NUMBERS FOR ASSEMBLY REFERENCE.

REQ'D	ITEM	PART NUMBER	DESCRIPTION	SYM.
2	3	HD113-2	HEATSINK, SEMI CONDUCTOR	Q1, Q3
X	2	BS 100	SOLDER, TIN ALLOY	
1	1	PC 376	PRINTED CIRCUIT BOARD	

LIST OF MATERIAL

QTY / UNIT	MODEL USED ON	ASS'Y NO.
	RTTD - 4	
APPLICATION		
CODE	5401 - 451	
A		

NOTICE TO PERSONS RECEIVING THIS DRAWING
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UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES	
DECIMALS .X ± .05 .XX ± .01 .XXX ± .005	FRACTIONS 1/64 ANGLES 0° - 30'
MATERIAL	
FINISH	

FINAL APPROVAL	DATE
<i>[Signature]</i>	9/15/69
MECH. DES.	DATE
<i>[Signature]</i>	7-15-69
ELECT. DES.	DATE
<i>[Signature]</i>	9/12/69
CHECKED	DATE
<i>[Signature]</i>	9/12/69
DRAWN	DATE
<i>[Signature]</i>	9/12/69

THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK			
PC 376 ASSEMBLY +5V, +28V POWER SUPPLY			
SIZE	CODE IDENT. NO.	DWG NO.	ISSUE
B	82679	A 4599	Ø

SCALE	SHEET	OF